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DOCKET NO. 2336-153

PATENTS ONLY

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy there

1. Name of conveying party(ies):

1. Seok Taek JUN
2. Young Keun LEE
3. Ik Seo CHOI

2. Name and address of receiving party(ies):

Name: Samsung Electro-Mechanics Co., Ltd.

Internal Address:

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

Street Address: 314 Maetan-3-dong, Paldal-ku

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
- ☐ Security Agreement ☐ Change of Name
- ☐ Other

City: Suwon

State: Kyungki-do

Zip:

Country: Republic of Korea

Execution Date: December 30, 2002

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is: December 30, 2002

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

10/340590

5. Name and address of party to whom correspondence concerning document should be mailed:

Name:

LOWE HAUPTMAN GILMAN & BERNER

Internal Address:

Street Address: 1700 Diagonal Road, Suite 300

City: Alexandria

State: VA

Zip: 22314

6. Total number of applications and patents involved: one

7. Total fee (37 CFR 3.41) \$ 40.00

- ☐ Enclosed
- ☐ Authorized to be charged to deposit account
- ☒ Credit Card payment form enclosed

8. Deposit account number: 07-1337

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9. Signature:

Benjamin J. Hauptman, 29,310

Name of Person, Registration No.

Signature

January 13, 2003

Date

Total number of pages including cover sheet, attachment, and document: 3

CMB No. 0851-0011 (exp. 4/94)

JC715 U.S. PTO
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40.00 DP

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>JUN, Seok Taek</u>	(4) _____
(2) <u>LEE, Young Keun</u>	(5) _____
(3) <u>CHOI, Ik Seo</u>	(6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG ELECTRO-MECHANICS CO., LTD.
314 Maetan-3-dong, Paldal-ku, Suwon,
Kyungki-do, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled CERAMIC MULTILAYER SUBSTRATE AND METHOD FOR MANUFACTURING THE SAME

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____;

or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTOR(S)

DATE SIGNED

1) JUN
Name: JUN, Seok Taek

December 30, 2002

2) LEE Y. K
Name: LEE, Young Keun

December 30, 2002

3) CHOI. I. S
Name: CHOI, Ik Seo

December 30, 2002